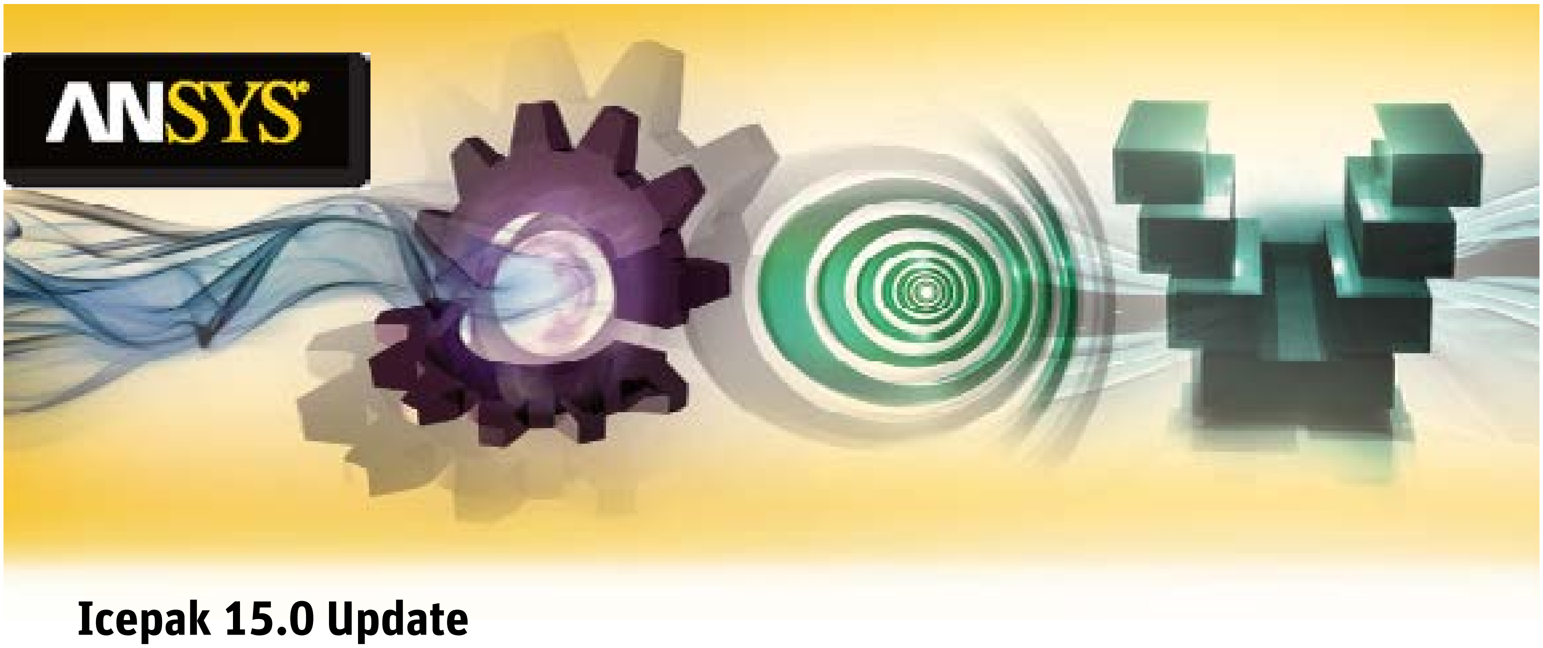
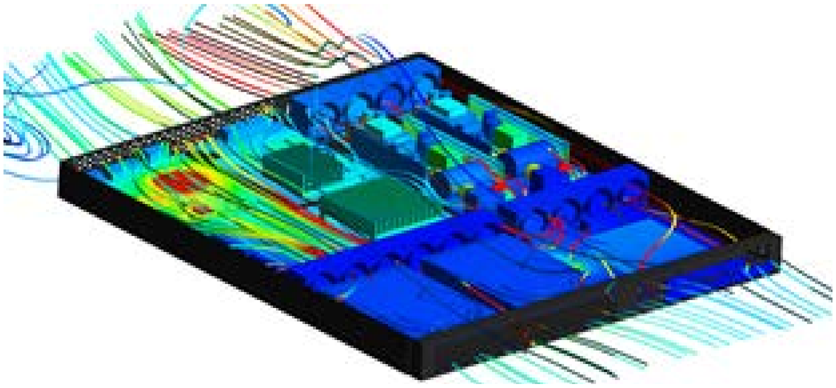


Icepak 15.0 Update

In this training, you will learn about the new electronics cooling capabilities offered with ANSYS Icepak 15.0. The update will include a presentation on the improvements in usability for electronics cooling simulation, new options for optimization and parametric analysis, and modeling the mixing and transport of multiple species. During this presentation, you will also learn about innovations in multiphysics coupling of electromagnetics and thermal simulation for increasing the fidelity of electronic designs. In addition, the training will highlight preprocessing, solver, postprocessing, and macro enhancements in ANSYS 15.0.

There will be a Q&A session after the update presentation. Past experience with Icepak is desired.



Location: Ann Arbor, MI

Date: May 2, 2014

Time: 10:00 a.m. – 2:00 p.m.

Venue:
ANSYS, Inc.
900 Victors Way
Atrium One
Suite 350
Ann Arbor, MI 48108

Cost: **Free - Space is limited.**

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